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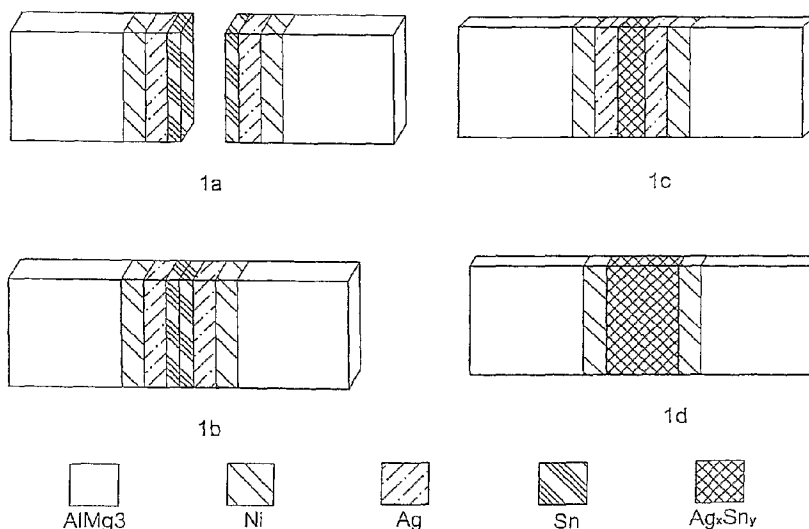
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(54) Title: METHOD OF CONNECTING MODULE LAYERS SUITABLE FOR THE PRODUCTION OF MICROSTRUCTURE COMPONENTS AND A MICROSTRUCTURE COMPONENT



(57) Abstract: For the purpose of ensuring that the pressure and corrosion resistance of microstructure components is high enough, that the component's tightness against fluid exiting from the component or fluid spilling over into adjacent microchannels is high enough, that the microchannels have a sufficiently low flow resistance, and for the purpose of ensuring cost-effectiveness of the manufacturing method, a method for joining microstructured component layers is described, the method comprising the following method steps: a) at least one multifunctional barrier coating is applied at least at the joining surfaces of microstructured component layers made of aluminum and/or aluminum alloys, copper/copper alloys, and/or high-grade steels, b) at least one solder/brazing coating is applied to the at least one barrier coating, c) the component layers are stacked, and d) are then soldered/brazed using heat.

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